

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE8457DLE	**Issued**	4. July 2019
MA#	MA002422484		
Package	PG-TSON-8-1	**Weight***	26.94 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.221	4.53	4.53	45325	45325
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		438	
	non noble metal	iron	7439-89-6	0.236	0.88		8763	
	non noble metal	copper	7440-50-8	9.586	35.58	36.51	355825	365136
wire	non noble metal	copper	7440-50-8	0.040	0.15	0.15	1477	1477
encapsulation	organic material	carbon black	1333-86-4	0.030	0.11		1109	
	plastics	epoxy resin	-	1.539	5.71		57128	
	inorganic material	silicondioxide	60676-86-0	13.373	49.65	55.47	496403	554640
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14187	14187
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1614	1614
glue	plastics	epoxy resin	-	0.119	0.44		4405	
	noble metal	silver	7440-22-4	0.356	1.32	1.76	13216	17621
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com